



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECEIVED
TECHNOLOGY CENTER
APR 11 2002

Applicant: Cho, Sung Dae
Assignee: Samsung Electronics Co., Ltd.
Title: Reel-Deployed Printed Circuit Board (As Amended)
Serial No.: 09/827,112 Filing Date: April 5, 2001
Examiner: J. Alcala Group Art Unit: 2827
Docket No.: AB-698-1D US

San Jose, California
April 11, 2002

COMMISSIONER FOR PATENTS
WASHINGTON, D. C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the Office Action mailed January 17, 2002, Applicants respectfully request the Examiner to reconsider the application in view of the remarks set forth below.

IN THE TITLE

Please amend the title by deleting "And Method For Manufacturing Chip-On-Board Packages." The amended title should now recite "Reel-Deployed Printed Circuit Board."

IN THE SPECIFICATION

Please amend the specification as indicated in Attachment A. The following paragraph is a clean version of the new paragraph.

Please insert the following paragraph after line 2 on page 1:

CROSS REFERENCE TO RELATED APPLICATIONS

This application is a divisional of and claims priority from U.S. Patent Application No. 09/219,407, filed on December 23, 1998, which has issued as U.S. Patent No. 6,235,555.

LAW OFFICES OF
SEJUNVEN HERRILL
MACPHERSON LLP

25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979

04/16/2002 CNGUYEN

01 FC:103

125.00 CH

848643 v1